

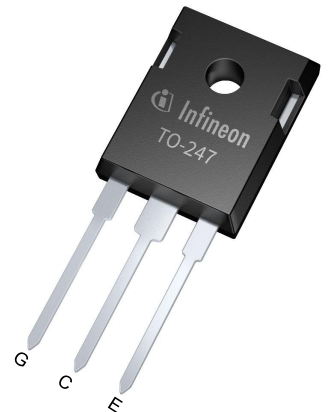
Reverse-Conducting IGBT with monolithic body diode

Features

- $V_{CE} = 650\text{ V}$
- $I_C = 30\text{ A}$
- Powerful monolithic diode optimized for ZCS applications
- High ruggedness, temperature stable behavior
- Very low V_{CEsat} and low E_{off}
- Easy paralleling capability due to positive temperature coefficient in V_{CEsat}
- Low EMI
- Low electrical parameters depending (dependence) on temperature
- Qualified according to JESD-022 for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models: <http://www.infineon.com/igbt/>

Potential applications

- Welding
- PFC
- ZCS - converters



Lead-Free



Green

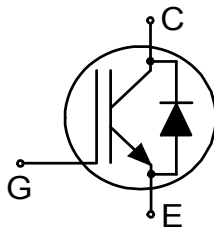


Halogen-Free



RoHS

Description



Type	Package	Marking
IKW30N65WR5	PG-TO247-3	K30EWR5

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1 Package

Table 1 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Internal emitter inductance measured 5 mm (0.197 in.) from case	L_E			13.0		nH
Storage temperature	T_{stg}		-55		150	°C
Soldering temperature		wave soldering 1.6 mm (0.063 in.) from case for 10 s			260	°C
Mounting torque	M	M3 screw Maximum of mounting process: 3			0.6	Nm
Thermal resistance, junction-ambient	$R_{th(j-a)}$				40	K/W

2 IGBT

Table 2 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Collector-emitter voltage	V_{CE}	$T_{vj} \geq 25\text{ °C}$	650	V	
DC collector current, limited by T_{vjmax}	I_C		$T_c = 25\text{ °C}$	60	A
			$T_c = 117\text{ °C}$	30	
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpulse}		90	A	
Turn-off safe operating area		$V_{CE} \leq 650\text{ V}, T_{vj} \leq 175\text{ °C}$	90	A	
Gate-emitter voltage	V_{GE}		± 20	V	
Transient gate-emitter voltage	V_{GE}	$t_p \leq 10\text{ }\mu\text{s}, D < 0.01$	± 30	V	
Power dissipation	P_{tot}		$T_c = 25\text{ °C}$	185	W
			$T_c = 117\text{ °C}$	75	

Table 3 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter breakdown voltage	V_{BRCES}	$I_C = 0.2\text{ mA}, V_{GE} = 0\text{ V}$	650			V
Collector-emitter saturation voltage	V_{CEsat}	$I_C = 30\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$	1.4	1.8	V
			$T_{vj} = 175\text{ °C}$	1.65		
Gate-emitter threshold voltage	V_{GEth}	$I_C = 0.3\text{ mA}, V_{CE} = V_{GE}$	3.2	4	4.8	V

(table continues...)
Datasheet

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Zero gate-voltage collector current	I_{CES}	$V_{CE} = 650 \text{ V}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25 \text{ }^\circ\text{C}$			40	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}$				100	nA
Transconductance	g_{fs}	$I_C = 30 \text{ A}, V_{CE} = 20 \text{ V}$			35		S
Input capacitance	C_{ies}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1000 \text{ kHz}$			3700		pF
Output capacitance	C_{oes}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1000 \text{ kHz}$			35		pF
Reverse transfer capacitance	C_{res}	$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1000 \text{ kHz}$			16		pF
Gate charge	Q_G	$I_C = 30 \text{ A}, V_{GE} = 15 \text{ V}, V_{CC} = 520 \text{ V}$			155		nC
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		39		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		35		
Rise time (inductive load)	t_r	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		12		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		14		
Turn-off delay time	$t_{d(off)}$	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		367		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		484		
Fall time (inductive load)	t_f	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		9		ns
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		9		
Turn-on energy	E_{on}	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		0.47		mJ
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		0.53		
Turn-off energy	E_{off}	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		0.1		mJ
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		0.22		
Total switching energy	E_{ts}	$V_{CC} = 400 \text{ V}, V_{GE} = 0/15 \text{ V}, R_{Gon} = 26 \text{ } \Omega, R_{Goff} = 26 \text{ } \Omega, L_\sigma = 45 \text{ nH}, C_\sigma = 32 \text{ pF}$	$T_{vj} = 25 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		0.57		mJ
			$T_{vj} = 175 \text{ }^\circ\text{C}, I_C = 15 \text{ A}$		0.75		

(table continues...)

Table 3 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
IGBT thermal resistance, junction to case	$R_{th(j-c)}$				0.81	K/W
Operating junction temperature	T_{vj}		-40		175	°C

Note: Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified.

3 Diode

Table 4 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25^\circ\text{C}$	650	V	
Diode forward current, limited by T_{vjmax}	I_F		$T_c = 25^\circ\text{C}$	24	A
			$T_c = 100^\circ\text{C}$	15	
Diode pulsed current, t_p limited by T_{vjmax}	I_{Fpulse}		45	A	

Table 5 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Diode forward voltage	V_F	$I_F = 15\text{ A}$	$T_{vj} = 25^\circ\text{C}$	1.4	1.9	V
			$T_{vj} = 175^\circ\text{C}$	1.5		
Diode reverse recovery time	t_{rr}	$V_R = 400\text{ V}$	$T_{vj} = 25^\circ\text{C}$, $I_F = 15\text{ A}$, $-di_F/dt = 900\text{ A}/\mu\text{s}$	95		ns
			$T_{vj} = 175^\circ\text{C}$, $I_F = 15\text{ A}$, $-di_F/dt = 900\text{ A}/\mu\text{s}$	121		
Diode reverse recovery charge	Q_{rr}	$V_R = 400\text{ V}$	$T_{vj} = 25^\circ\text{C}$, $I_F = 15\text{ A}$, $-di_F/dt = 900\text{ A}/\mu\text{s}$	1.25		μC
			$T_{vj} = 175^\circ\text{C}$, $I_F = 15\text{ A}$, $-di_F/dt = 900\text{ A}/\mu\text{s}$	2.15		

(table continues...)

Table 5 (continued) Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Diode peak reverse recovery current	I_{rrm}	$V_R = 400\text{ V}$	$T_{vj} = 25\text{ °C},$ $I_F = 15\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		22		A
					28		
Diode peak rate of fall of reverse recovery current	di_{rr}/dt	$V_R = 400\text{ V}$	$T_{vj} = 25\text{ °C},$ $I_F = 15\text{ A},$ $-di_F/dt = 900\text{ A}/\mu\text{s}$		590		A/ μs
					1100		
Diode thermal resistance, junction to case	$R_{th(j-c)}$					3.4	K/W
Operating junction temperature	T_{vj}			-40		175	°C

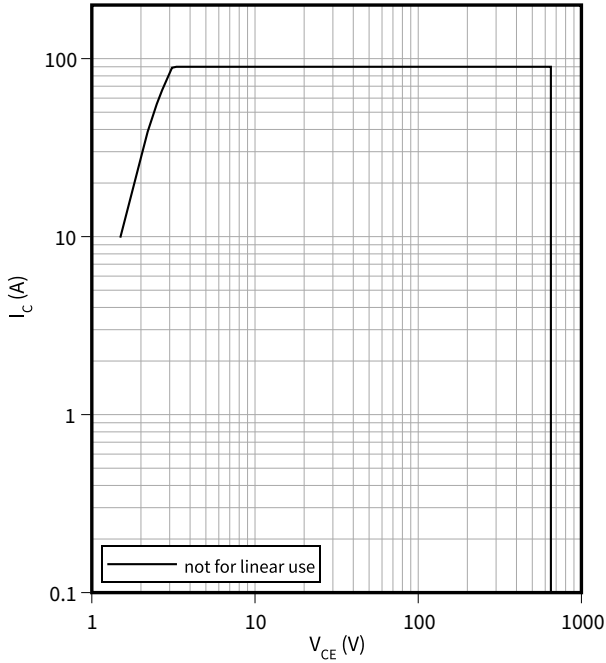
Note: For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

4 Characteristics diagrams

Reverse bias safe operating area

$$I_C = f(V_{CE})$$

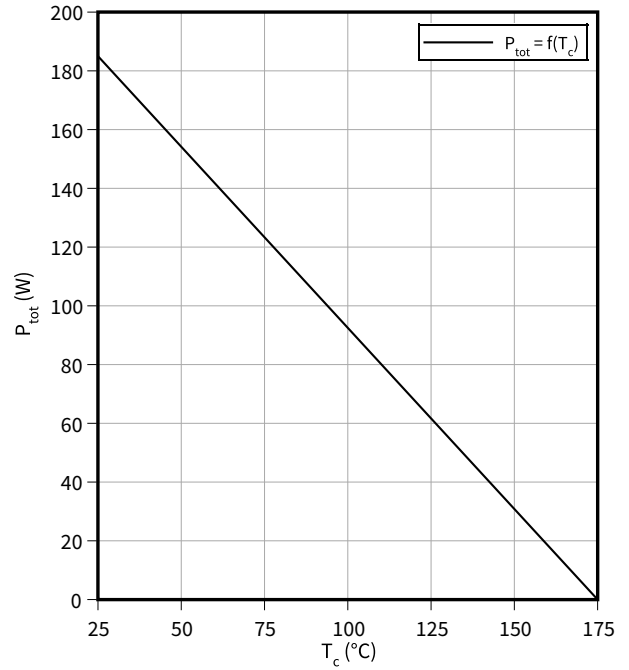
$$T_{vj} \leq 175\text{ °C}, V_{GE} = 15\text{ V}, T_c = 25\text{ °C}$$



Power dissipation as a function of case temperature

$$P_{tot} = f(T_c)$$

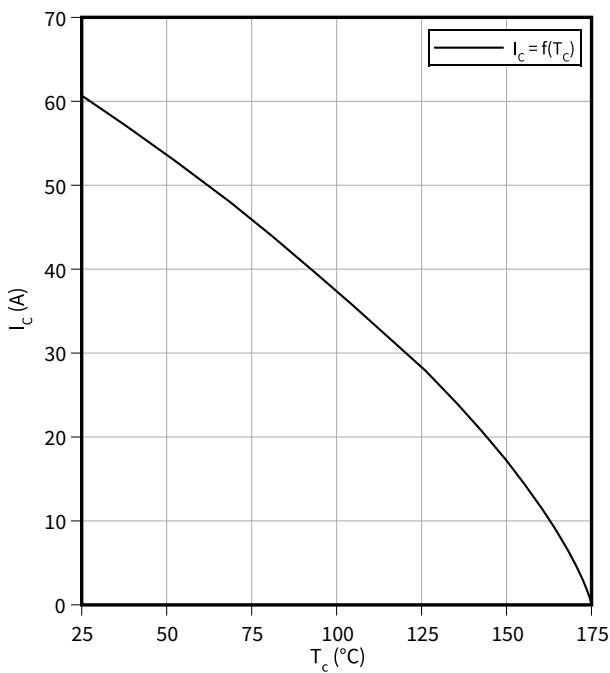
$$T_{vj} \leq 175\text{ °C}$$



Collector current as a function of case temperature

$$I_C = f(T_c)$$

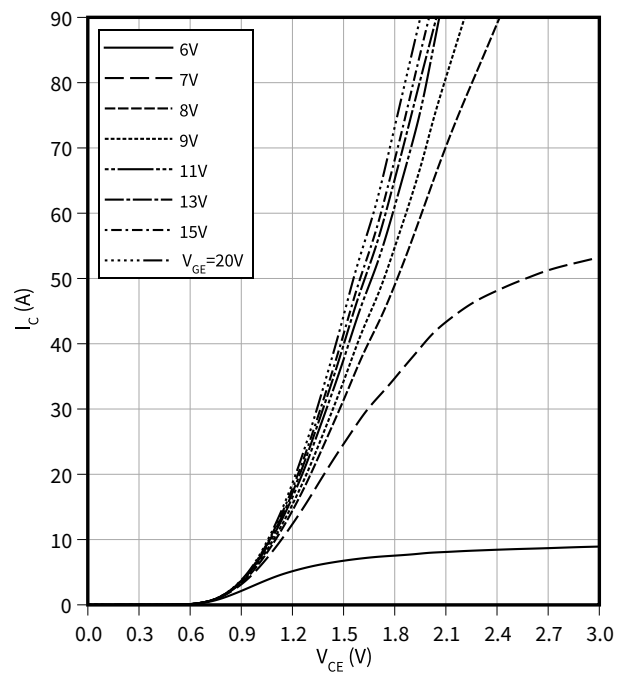
$$T_{vj} \leq 175\text{ °C}, V_{GE} \geq 15\text{ V}$$



Typical output characteristic

$$I_C = f(V_{CE})$$

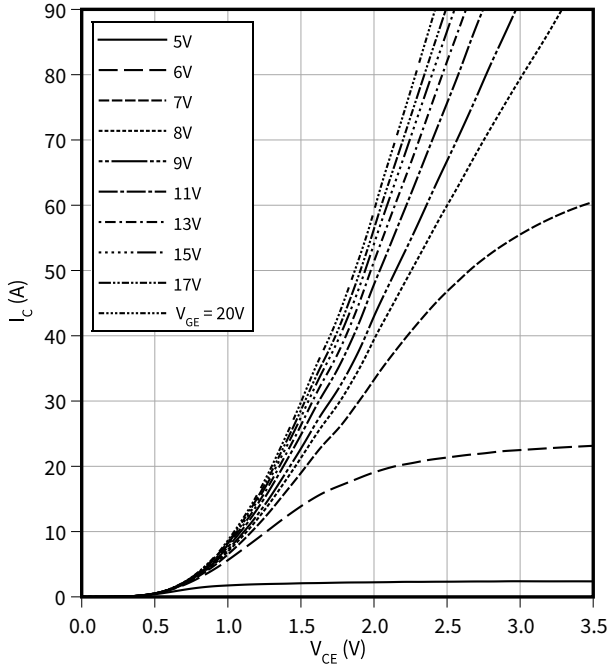
$$T_{vj} = 25\text{ °C}$$



4 Characteristics diagrams

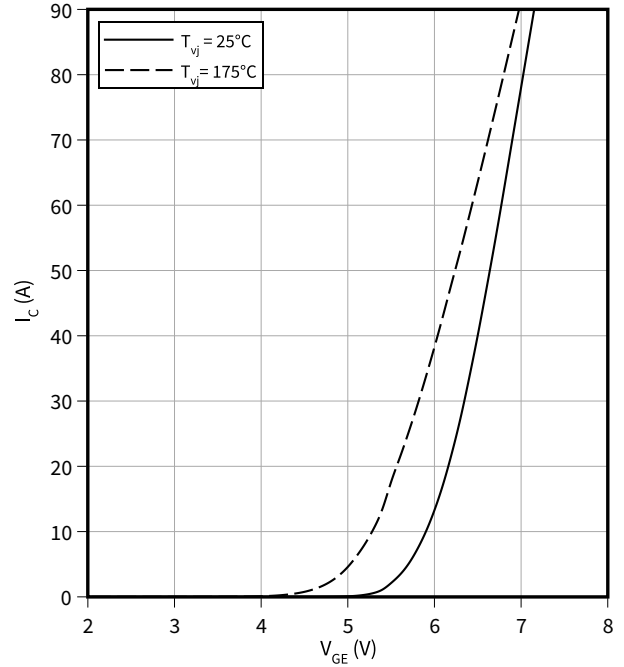
Typical output characteristic

$I_C = f(V_{CE})$
 $T_{vj} = 175\text{ °C}$



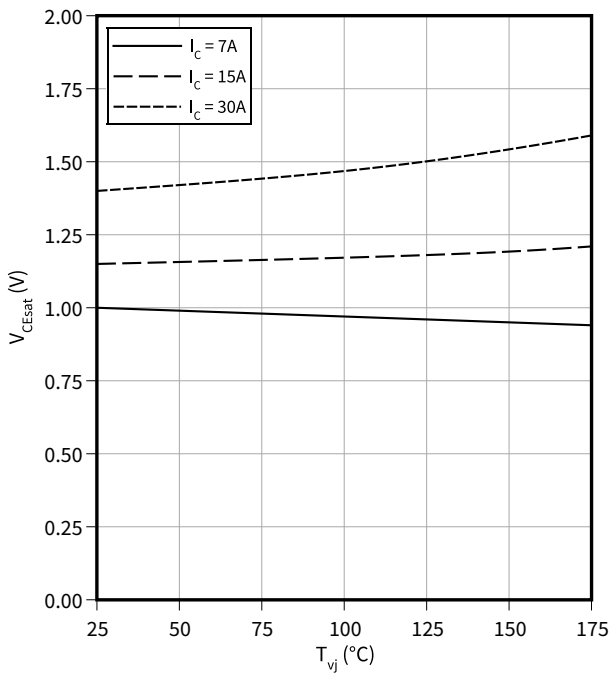
Typical transfer characteristic

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



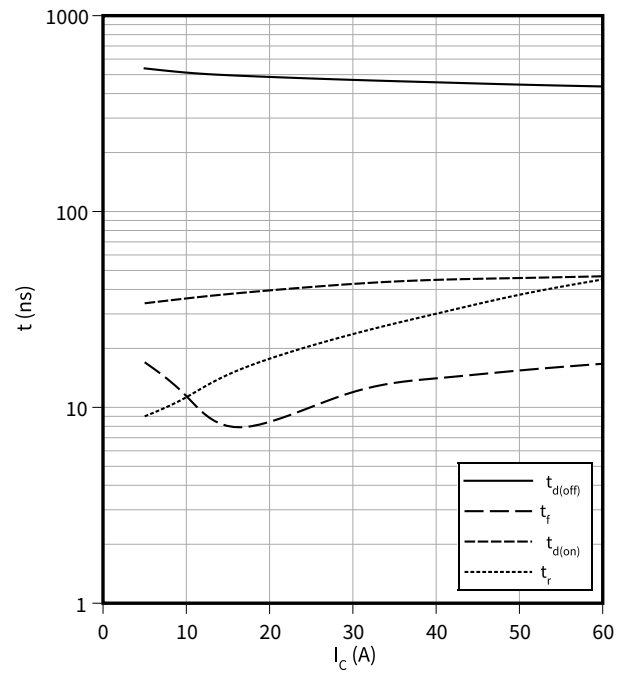
Typical collector-emitter saturation voltage as a function of junction temperature

$V_{CEsat} = f(T_{vj})$
 $V_{GE} = 15\text{ V}$



Typical switching times as a function of collector current

$t = f(I_C)$
 $V_{CC} = 400\text{ V}, T_{vj} = 175\text{ °C}, V_{GE} = 0/15\text{ V}, R_G = 26\text{ }\Omega$

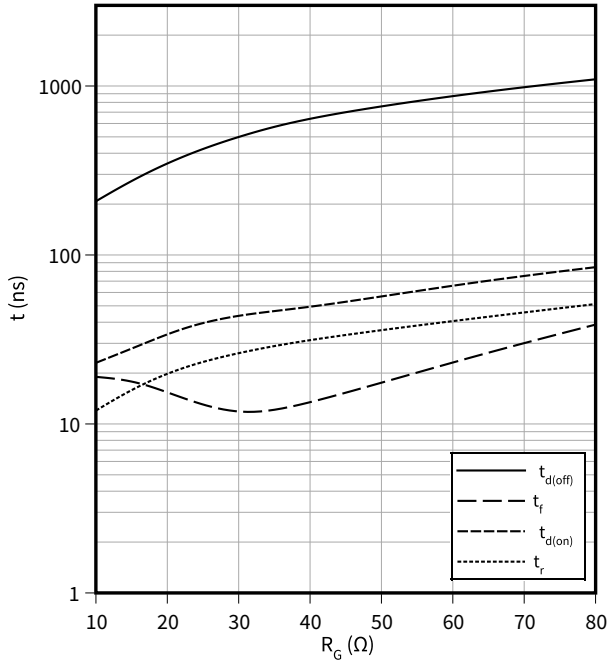


4 Characteristics diagrams

Typical switching times as a function of gate resistor

$t = f(R_G)$

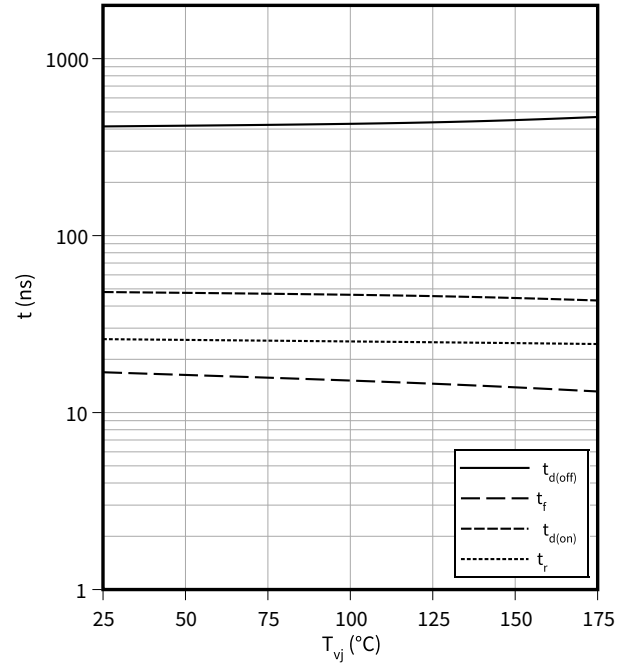
$I_C = 30\text{ A}$, $V_{CC} = 400\text{ V}$, $T_{vj} = 175\text{ °C}$, $V_{GE} = 0/15\text{ V}$



Typical switching times as a function of junction temperature

$t = f(T_{vj})$

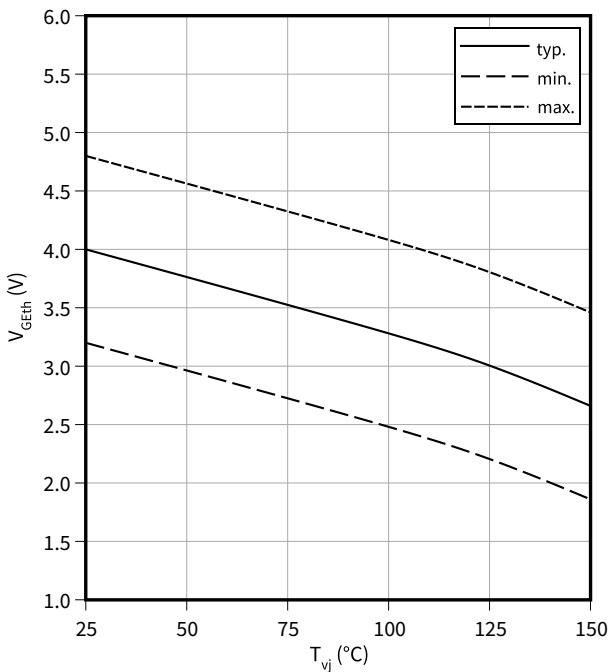
$I_C = 30\text{ A}$, $V_{CC} = 400\text{ V}$, $V_{GE} = 0/15\text{ V}$, $R_G = 26\text{ }\Omega$



Gate-emitter threshold voltage as a function of junction temperature

$V_{GEth} = f(T_{vj})$

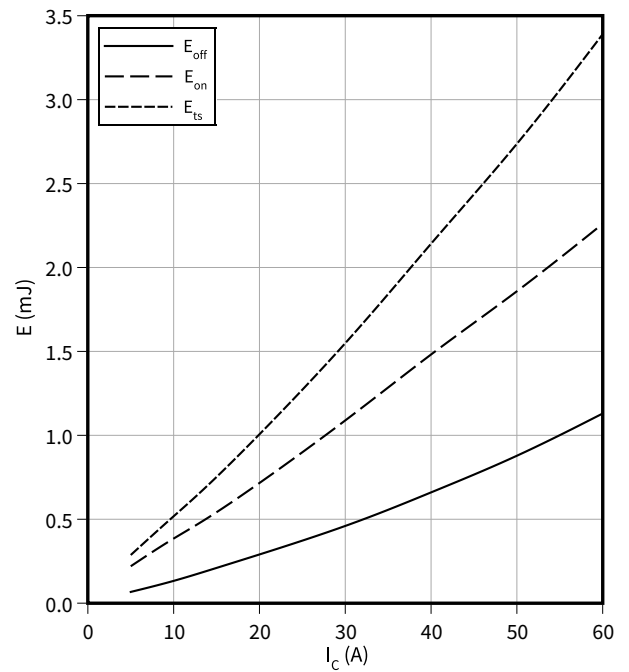
$I_C = 0.3\text{ mA}$



Typical switching energy losses as a function of collector current

$E = f(I_C)$

$V_{CC} = 400\text{ V}$, $T_{vj} = 175\text{ °C}$, $V_{GE} = 0/15\text{ V}$, $R_G = 26\text{ }\Omega$

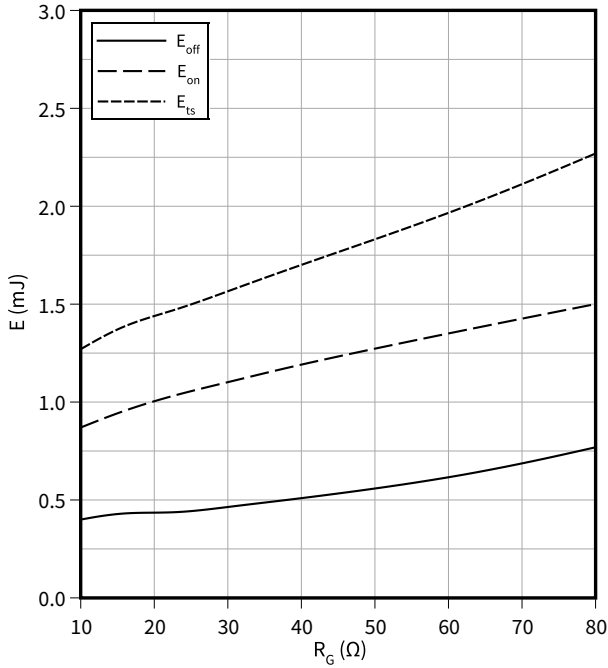


4 Characteristics diagrams

Typical switching energy losses as a function of gate resistor

$E = f(R_G)$

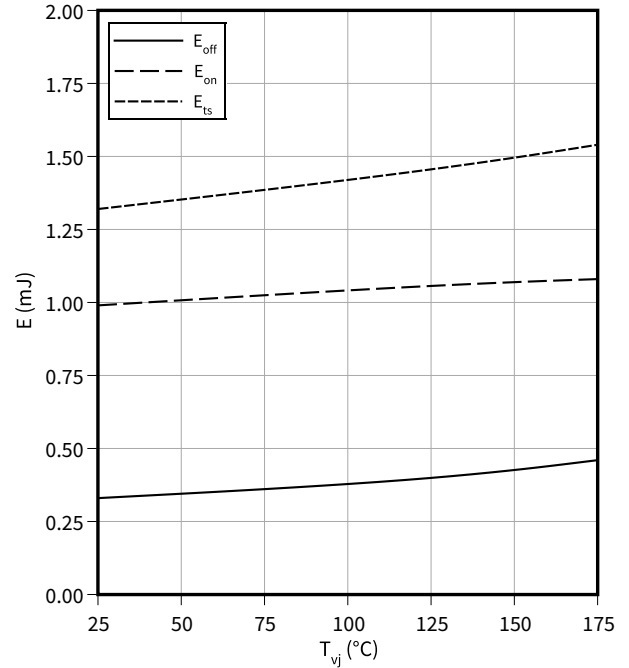
$I_C = 30\text{ A}$, $V_{CC} = 400\text{ V}$, $T_{vj} = 175\text{ }^\circ\text{C}$, $V_{GE} = 0/15\text{ V}$



Typical switching energy losses as a function of junction temperature

$E = f(T_{vj})$

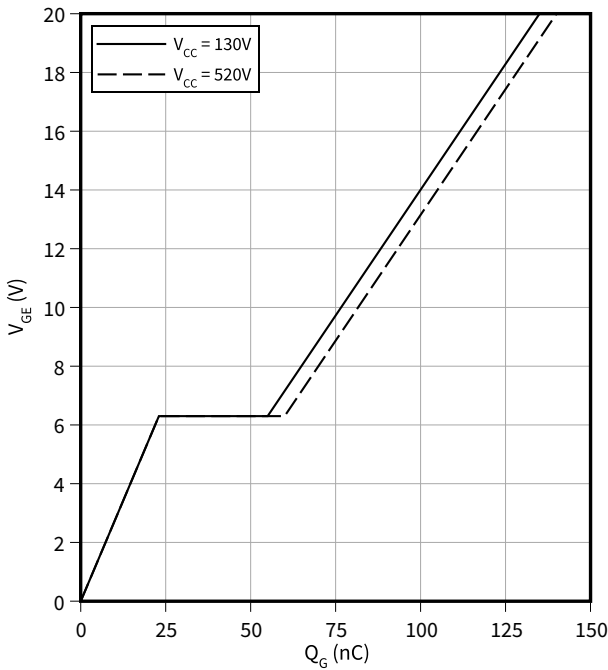
$I_C = 30\text{ A}$, $V_{CC} = 400\text{ V}$, $V_{GE} = 0/15\text{ V}$, $R_G = 26\text{ }\Omega$



Typical gate charge

$V_{GE} = f(Q_G)$

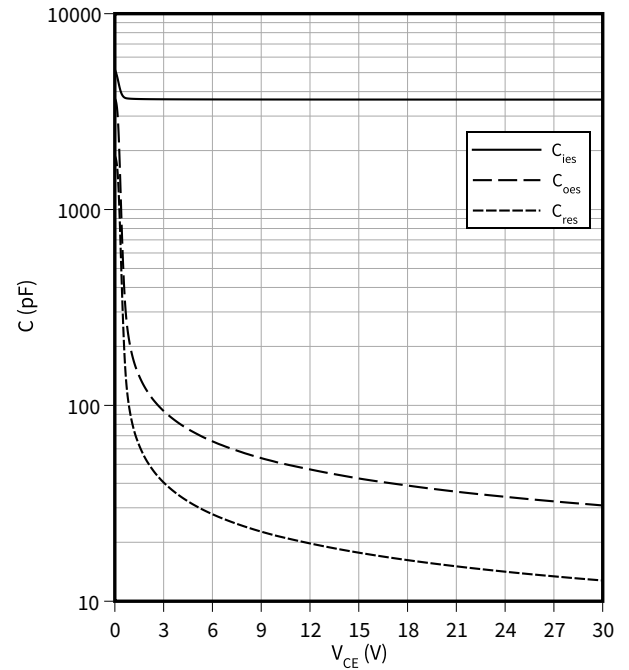
$I_C = 30\text{ A}$



Typical capacitance as a function of collector-emitter voltage

$C = f(V_{CE})$

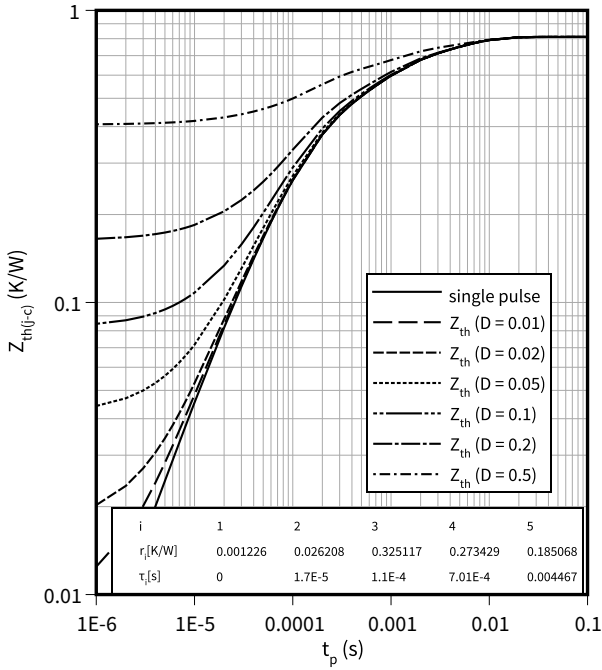
$f = 1000\text{ kHz}$, $V_{GE} = 0\text{ V}$



4 Characteristics diagrams

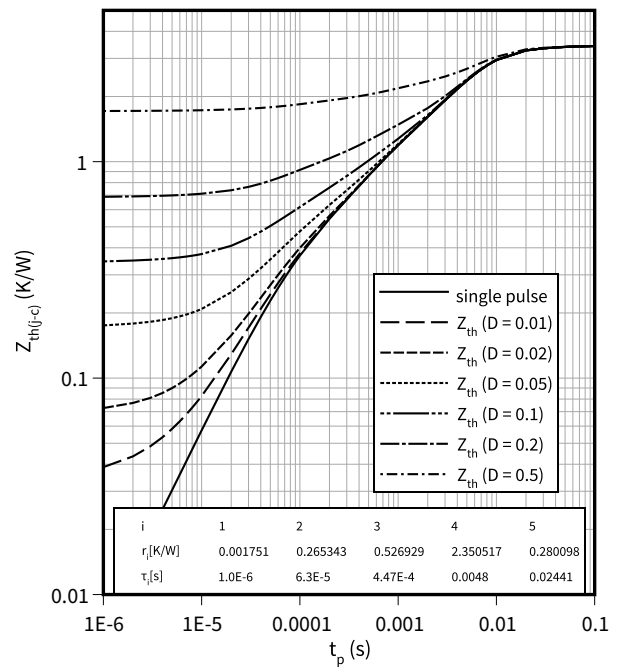
IGBT transient thermal impedance as a function of pulse width

$Z_{th(j-c)} = f(t_p)$
 $D = t_p/T$



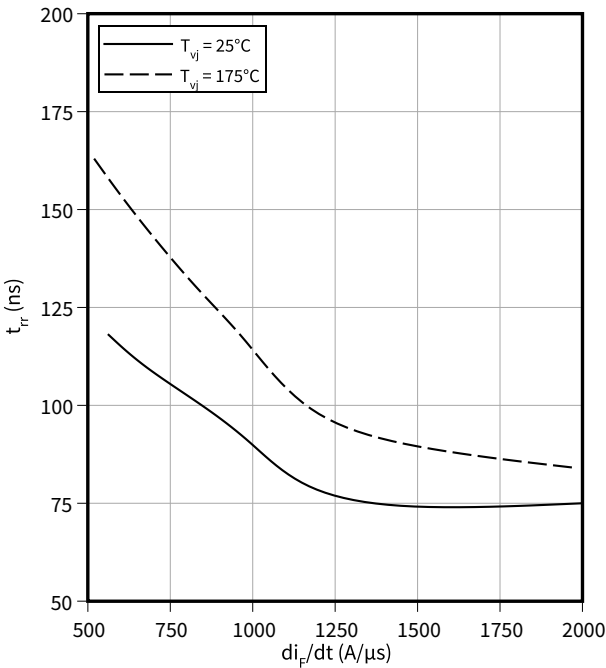
Diode transient thermal impedance as a function of pulse width

$Z_{th(j-c)} = f(t_p)$
 $D = t_p/T$



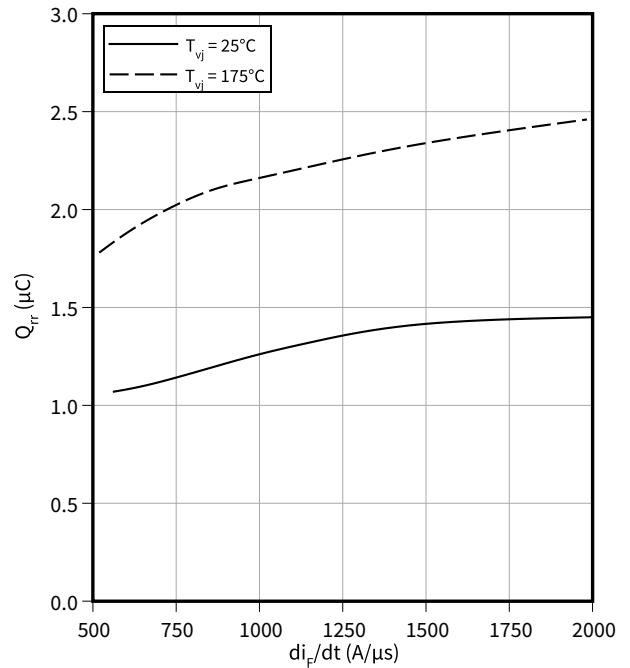
Typical reverse recovery time as a function of diode current slope

$t_{rr} = f(di_F/dt)$
 $V_R = 400 \text{ V}, I_F = 15 \text{ A}$



Typical reverse recovery charge as a function of diode current slope

$Q_{rr} = f(di_F/dt)$
 $V_R = 400 \text{ V}, I_F = 15 \text{ A}$

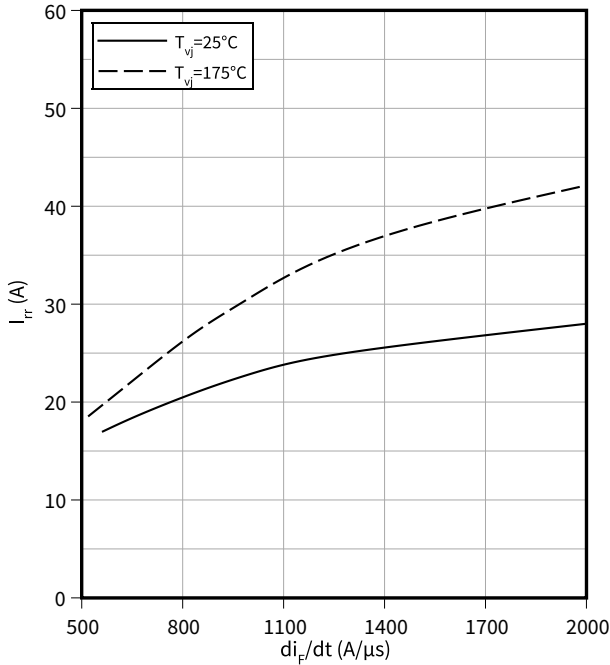


4 Characteristics diagrams

Typical reverse recovery current as a function of diode current slope

$I_{rr} = f(di_F/dt)$

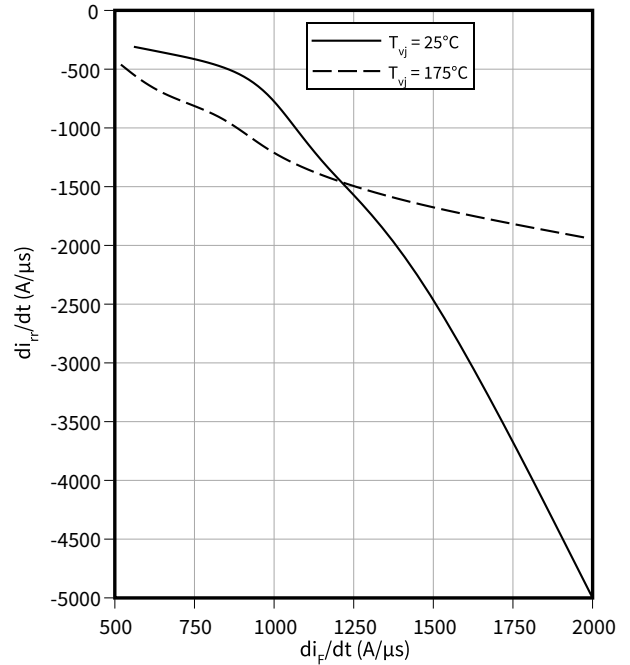
$V_R = 400\text{ V}, I_F = 15\text{ A}$



Typical diode peak rate of fall of reverse recovery current as a function of diode current slope

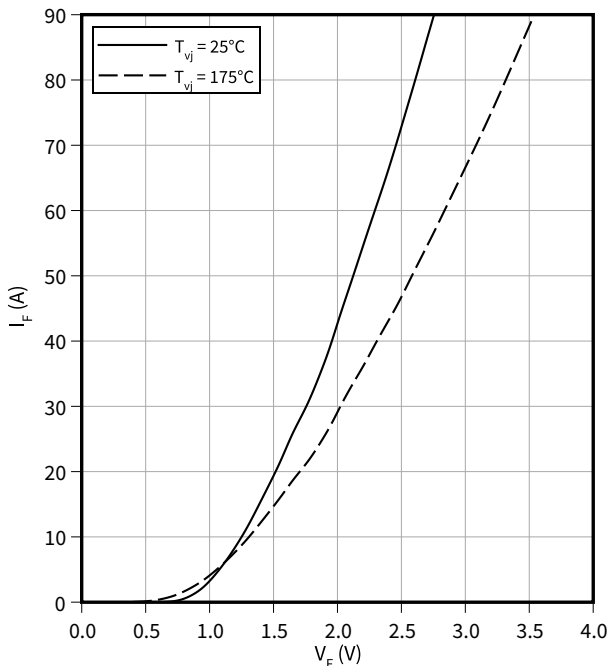
$di_{rr}/dt = f(di_F/dt)$

$V_R = 400\text{ V}, I_F = 15\text{ A}$



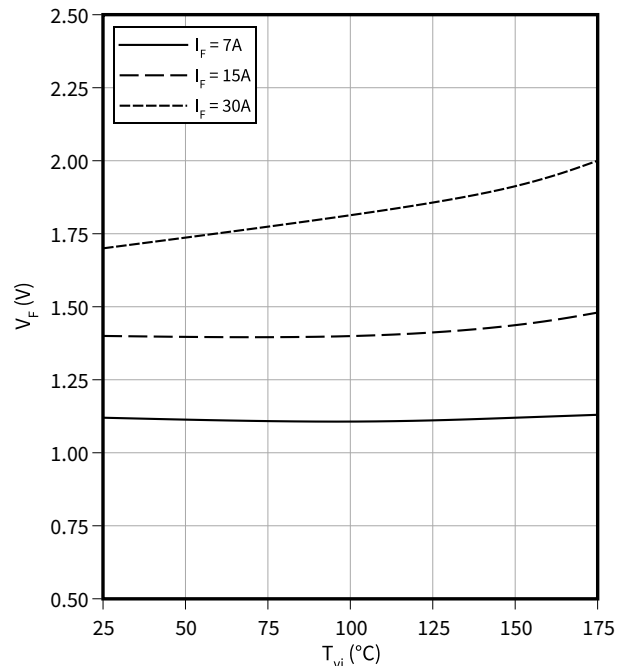
Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



Typical diode forward voltage as a function of junction temperature

$V_F = f(T_{vj})$



5 Package outlines

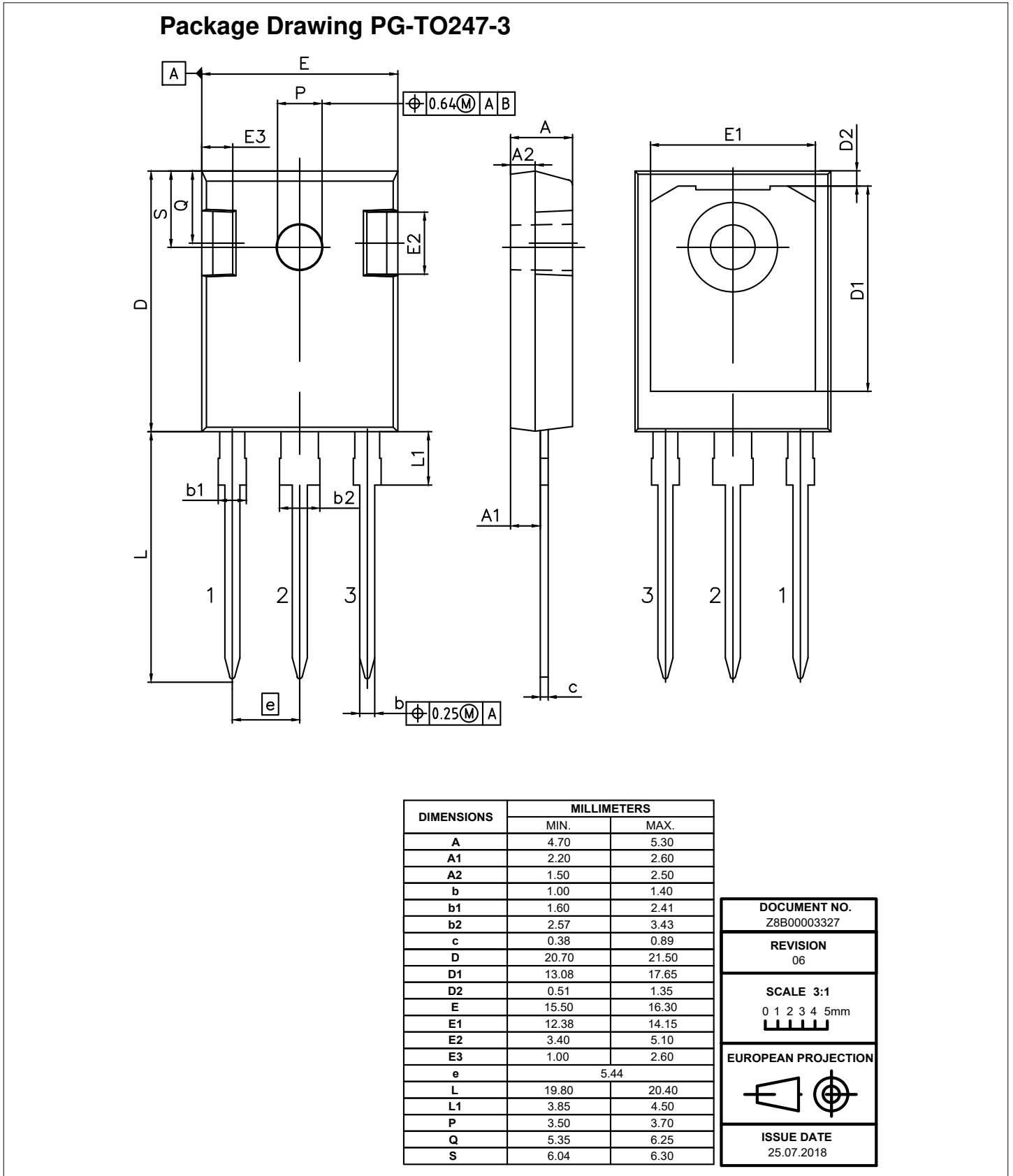


Figure 1

6 Testing conditions

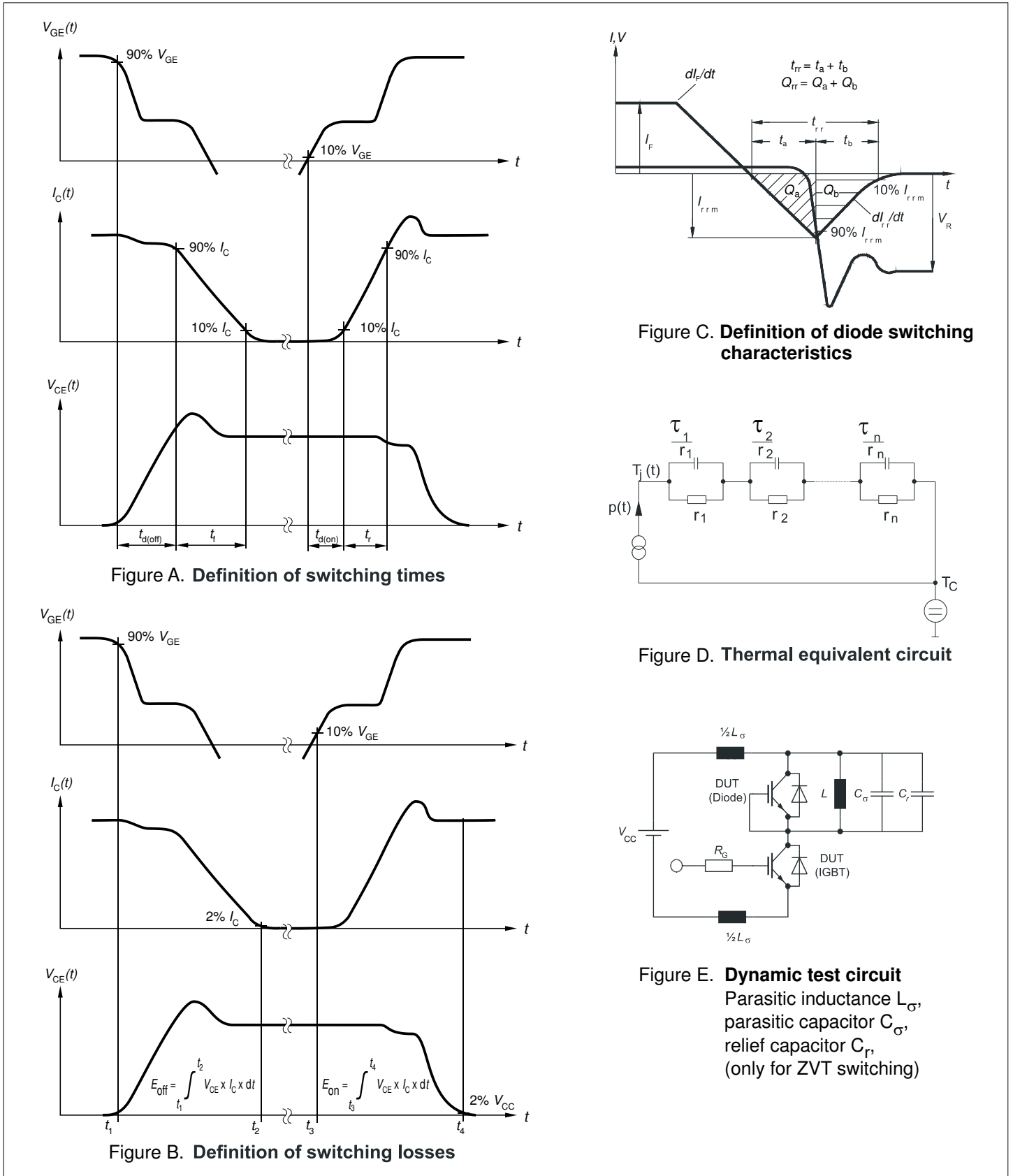


Figure 2

Revision history

Document revision	Date of release	Description of changes
V1.1	2015-04-23	Preliminary data sheet
V1.2	2015-05-12	Minor change Figure 3
V1.3	2015-06-01	Update Figure 14 E(T)
V2.1	2015-12-10	Final data sheet
V2.2	2016-10-14	New switching parameters for IGBT at $I_c=15A$
n/a	2020-11-30	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
1.10	2022-03-08	Added transient gate-emitter voltage
1.20	2022-05-06	Transient gate-emitter voltage V_{GE} added in table "Maximum rated values" of IGBT Update of switching energy values in table "Characteristic values" "Forward bias safe operating area" diagram renamed to "Reverse bias safe operating area"

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